

SESSION 7b: PACKAGING

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This section includes papers on current and emerging issues in III-V packaging. The first invited paper from M/A-COM Technology Solutions, covers all aspects of millimeter wave surface mount packages for high frequency and high power applications. Viability of custom surface mount packaging as it compares to traditional packaging is discussed. The hot topic of cost reduction by replacing bonded wire assemblies without compromising performance and reliability is discussed in detail.

Second, GCS presents a paper discussing wafer fabrication issues not typically discussed in conferences, but of importance to every foundry fabricating circuits with gold based bond pads. They provide detail on repeatable way to remove TiO_x residue.

The final paper from WIN Semi on copper bump technology is a paper on practical issues very relevant to III-V products. Manufacturability, yield and cost issues in implementing copper bumps in large volume production are discussed.